8-bit Proprietary Microcontrollers

CMOS

F²MC-8FX MB95100A Series

MB95107A/F108AS/F108AW/FV100A-101

■ DESCRIPTION

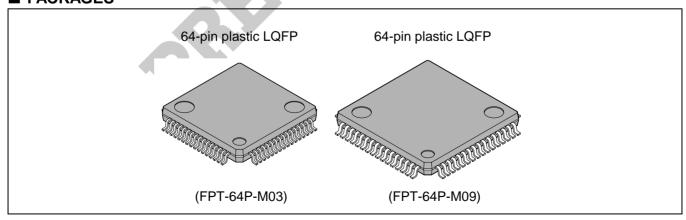
The MB95100A series is general-purpose, single-chip microcontrollers. In addition to a compact instruction set, the microcontrollers contain a variety of peripheral functions.

■ FEATURE

- F2MC-8FX CPU core
 - Instruction set optimized for controllers
 - Multiplication and division instructions
 - 16-bit arithmetic operations
 - · Bit test branch instruction
 - Bit manipulation instructions etc.
- Clock
 - · Main clock
 - · Main PLL clock
 - Subclock (for dual clock product)
 - Sub PLL clock (for dual clock product)

(Continued)

■ PACKAGES





- Timer
 - 8/16-bit compound timer × 2 channels
 - 16-bit reload timer
 - 8/16-bit PPG × 2 channels
 - 16-bit PPG × 2 channels
 - Timebase timer
 - Watch prescaler (for dual clock product)
- LIN-UART
 - Full duplex double buffer
 - · Clock asynchronous or synchronous serial transfer capable
- UART/SIO
 - · Clock asynchronous or synchronous serial transfer capable
- I2C*
 - · Built-in wake-up function
- External interrupt
 - Interrupt by edge detection (rising, falling, or both edges can be selected)
 - Can be used to recover from low-power consumption modes.
- 10-bit A/D converter
 - 10-bit resolution
- Low-power consumption (standby mode)
 - · Stop mode
 - Sleep mode
 - Watch mode (for dual clock product)
 - Timebase timer mode
- I/O port: Max 55
 - General-purpose I/O ports (Nch open drain) : 6 ports
 - General-purpose I/O ports (CMOS) : 49 ports
- *: Purchase of Fujitsu I²C components conveys a license under the Philips I²C Patent Rights to use, these components in an I²C system provided that the system conforms to the I²C Standard Specification as defined by Philips.

■ PRODUCT LINEUP

	Part number						
Par	ameter	MB95107A	MB95F108AS	MB95F108AW	MB95FV100A-101		
Тур	oe	MASK product	FLASH	FLASH product			
RO	M capacity	48 KB		60 KB			
RA	M capacity		2 KB 3.75 K				
Res	set output		N	lo			
Opt	ion	Selectable Single/Dual -system*²	Single-system	Dual-system	Selectable Single/Dual -system*1		
CP	U functions	Instruction bit length Instruction length Data bit length Minimum instruction					
	Ports (Max 55 ports)	General-purpose I/O General-purpose I/O	port (Nch open drain port (CMOS))	: 6 ports : 49 ports		
	Timebase timer	Interrupt cycle: 0.5 ms, 2.05 ms, 8.2 ms, 32.8 ms (at main oscillation clock 4 MHz)					
	Watchdog timer	Reset generated cycle At main oscillation clock 10 MHz : Min 105 ms At sub oscillation clock 32.768 kHz (for dual clock product) : Min 250 ms					
	Wild register	Capable of replacing 3 bytes of data					
ctions	I ² C bus	Master/slave sending and receiving Bus error function and arbitration function Detecting transmitting direction function Start condition repeated generation and detection functions Built-in wake-up function					
Peripheral functions	UART/SIO	Data transfer capable in UART/SIO Full duplex double buffer, Variable data length (5/6/7/8-bit), built-in baud rate generator Transfer rate: 2400 bps to 125000 bps (at machine clock 10 MHz) NRZ type transfer format, error detected function LSB-first or MSB-first can be selected. Clock synchronous (SIO) or clock asynchronous (UART) data transfer capable					
	LIN-UART	Dedicated reload timer allowing a wide range of communication speeds to be set. Capable of data transfer synchronous or asynchronous to clock signal. LIN functions available as the LIN master or LIN slave.					
	A/D converter (12 channels)	8-bit or 10-bit resolution can be selected.					
	16-bit reload timer	Two clock modes and two counter operating modes can be selected. Square v form output Count clock: 7 internal clocks and external clock can be selected.					

	Part number							
Par	rameter	MB95107A	MB95F108AS	MB95F108AW	MB95FV100A-101			
	8/16-bit compound timer (2 channels)	× 1 channel". Built-in timer function waveform output	Built-in timer function, PWC function, PWM function, capture function and Square					
inctions	16-bit PPG (2 channels)	PWM mode or one-shot mode can be selected. Counter operating clock : Eight selectable clock sources Support for external trigger start						
Peripheral functions	8/16-bit PPG (2 channels)	Each channel of the PPG can be used as "8-bit PPG × 2 channels" or "16-bit PPG × 1 channel". Counter operating clock: Eight selectable clock sources						
Per	Watch counter (for dual clock product)	Count clock: Four selectable clock sources (125 ms, 250 ms, 500 ms, or 1 s) Counter value can be set from 0 to 63. (Capable of counting for 1 minute)						
	Watch prescaler (for dual clock product)	Four selectable interval times (125 ms, 250 ms, 500 ms, or 1 s)						
	External interrupt (12 channels)	Interrupt by edge detection (rising, falling, or both edges can be selected.) Can be used to recover from standby modes.						
Sta	ndby mode	by mode Sleep, stop, watch, and timebase timer						

^{*1 :} Change by the switch on MCU board.

^{*2 :} Specify clock mode when ordering MASK ROM.

■ SELECT OF OSCILLATION STABILIZATION WAIT TIME (MASK PRODUCT ONLY)

For the MASK product, you can set the mask option when ordering MASK ROM to select the initial value of main clock oscillation stabilization wait time from among the following four values.

Note that the EVA and FLASH products are fixed their initial value of main clock oscillation stabilization wait time at the maximum value.

Oscillation stabilization wait time	Remarks
(2 ² -2) /Fcн	0.5 μs (at main oscillation clock 4 MHz)
(2 ¹² -2) /Fcн	Approx. 1.02 ms (at main oscillation clock 4 MHz)
(2 ¹³ -2) /Fcн	Approx. 2.05 ms (at main oscillation clock 4 MHz)
(2 ¹⁴ -2) /Fcн	Approx. 4.10 ms (at main oscillation clock 4 MHz)

■ PACKAGES AND CORRESPONDING PRODUCTS

Part number Package	MB95107A	MB95F108AS	MB95F108AW	MB95FV100A-101
FPT-64P-M03	0	0	0	×
FPT-64P-M09	0	0	0	×
BGA-224P-M08	×	×	×	0

 \bigcirc : Available \times : Unavailable

■ DIFFERENCES AMONG PRODUCTS AND NOTES ON SELECTING PRODUCTS

• Notes on Using EVA Products

The EVA product has not only the functions of the MB95100A corresponding products series but also those of other products to support software development for multiple series and models of the F²MC-8FX family. The I/O addresses for peripheral resources not used by the MB95100A series are therefore access-barred. Read/write access to these access-barred addresses may cause peripheral resources supposed to be unused to operate, resulting in unexpected malfunctions of hardware or software.

Take particular care not to use word, long word, or similar access to read or write odd numbered bytes in the prohibited areas.

Note that the values read from barred addresses are different between the EVA product and the FLASH or MASK product. Therefore, the data must not be used for software processing.

The EVA product do not support the functions of some bits in single-byte registers. Read/write access to these bits does not cause hardware malfunctions. Since the EVA, FLASH, and MASK products are designed to behave completely the same way in terms of hardware and software, you do not have to pay special attention to specific products.

• Difference of Memory Spaces

If the amount of memory on the EVA product is different from that of the FLASH or MASK product, carefully check the difference in the amount of memory from the model to be actually used when developing software.

Current Consumption

- The current consumption of FLASH product is typically greater than for MASK ROM product.
- For details of current consumption, refer to "■ ELECTRICAL CHARACTERISTICS".

Package

For details of information on each package, see "■ PACKAGE DIMENSIONS".

Operating voltage

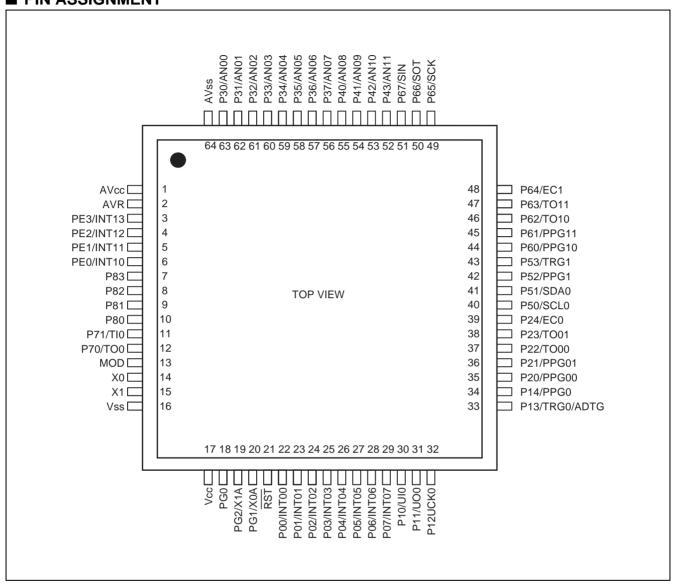
The operating voltage are different among the EVA, FLASH and MASK products.

For details of operating voltage, refer to "■ ELECTRICAL CHARACTERISTICS"

• Difference between RST and MOD pins

The RST and MOD pins are hysteresis inputs on the MASK product. A pull - down resistor is provided for the MOD pin of the MASK product.

■ PIN ASSIGNMENT



■ PIN DESCRIPTION

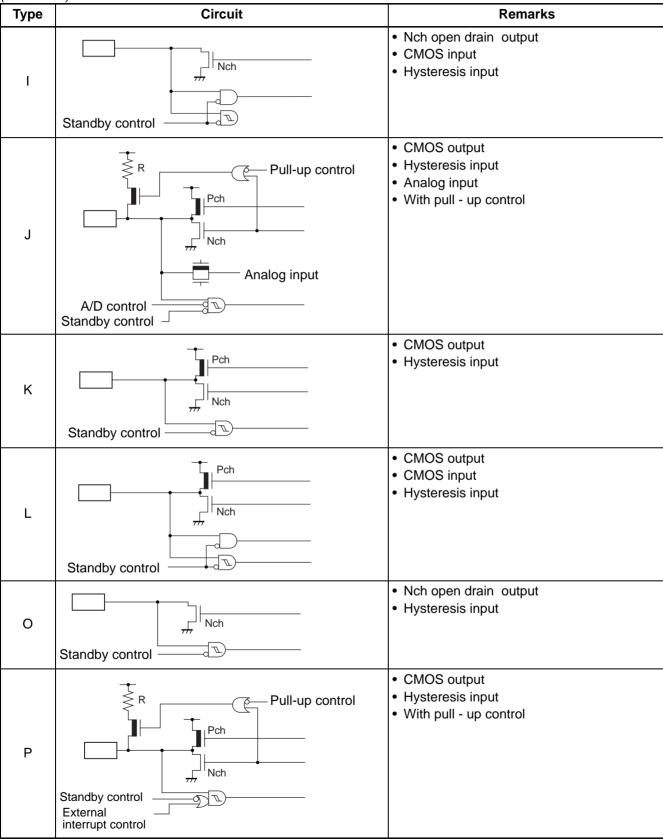
Pin no.	Pin name	Circuit type	Description	
1	AVcc	_	A/D power supply pin	
2	AVR	_	A/D reference input pin	
3	PE3/INT13			
4	PE2/INT12	P	General-purpose I/O port	
5	PE1/INT11		The pins are shared with the external interrupt input.	
6	PE0/INT10			
7	P83			
8	P82	0	Canaral numana I/O nort	
9	P81		General-purpose I/O port	
10	P80			
11	P71/TI0	Н	General-purpose I/O port. The pin is shared with 16 - bit reload timer ch0 output.	
12	P70/TO0		General-purpose I/O port. The pin is shared with 16 - bit reload timer ch0 input.	
13	MOD	В	An operating mode designation pin	
14	X0	A 0	Crystal application nin	
15	X1	A	Crystal oscillation pin	
16	Vss	_	Power supply pin (GND)	
17	Vcc	_	Power supply pin	
18	PG0	Н	General-purpose I/O port.	
19	PG2/X1A	H/A	Single-system product is general-purpose port.	
20	PG1/X0A	Π/A	Dual-system product is Crystal oscillation pin (32 kHz).	
21	RST	B'	Reset pin	
22	P00/INT00			
23	P01/INT01			
24	P02/INT02]		
25	P03/INT03	С	General-purpose I/O port.	
26	P04/INT04		The pins are shared with external interrupt input. Large current port.	
27	P05/INT05			
28	P06/INT06			
29	P07/INT07			
30	P10/UI0	G	General-purpose I/O port. The pin is shared with UART/SIO ch0 data input.	

Pin no.	Pin name	Circuit type	Description	
31	P11/UO0		General-purpose I/O port. The pin is shared with UART/SIO ch0 data output.	
32	P12/UCK0		General-purpose I/O port. The pin is shared with UART/SIO ch0 clock I/O.	
33	P13/TRG0/ ADTG	Н	General-purpose I/O port. The pin is shared with 16-bit PPG ch0 trigger input (TRG0) and A/D trigger input (ADTG).	
34	P14/PPG0		General-purpose I/O port. The pin is shared with 16-bit PPG ch0 output.	
35	P20/PPG00		General-purpose I/O port.	
36	P21/PPG01		The pins are shared with 8/16-bit PPG ch0 output.	
37	P22/TO00]] H	General-purpose I/O port.	
38	P23/TO01] ''	The pins are shared with 8/16-bit compound timer ch0 output.	
39	P24/EC0	_	General-purpose I/O port. The pin is shared with 8/16-bit compound timer ch0 clock input.	
40	P50/SCL0		General-purpose I/O port. The pin is shared with I ² C ch0 clock I/O.	
41	P51/SDA0	- 	General-purpose I/O port. The pin is shared with I ² C ch0 data I/O.	
42	P52/PPG1	. н	General-purpose I/O port. The pin is shared with 16-bit PPG ch1 output.	
43	P53/TRG1] "	General-purpose I/O port. The pin is shared with 16-bit PPG ch1 trigger input.	
44	P60/PPG10		General-purpose I/O port.	
45	P61/PPG11		The pins are shared with 8/16-bit PPG ch1 output.	
46	P62/TO10		General-purpose I/O port.	
47	P63/TO11		The pins are shared with 8/16-bit compound timer ch1 output.	
48	P64/EC1	K	General-purpose I/O port. The pin is shared with 8/16-bit compound timer ch1 clock input.	
49	P65/SCK		General-purpose I/O port. The pin is shared with LIN-UART clock I/O.	
50	P66/SOT		General-purpose I/O port. The pin is shared with LIN-UART data output.	
51	P67/SIN	L	General-purpose I/O port. The pin is shared with LIN-UART data input.	
52	P43/AN11			
53	P42/AN10		General-purpose I/O port.	
54	P41/AN09	- J	The pins are shared with A/D analog input.	
55	P40/AN08			

Pin no.	Pin name	Circuit type	Description	
56	P37/AN07			
57	P36/AN06			
58	P35/AN05			
59	P34/AN04	J	General-purpose I/O port.	
60	P33/AN03	J	The pins are shared with A/D analog input.	
61	P32/AN02			
62	P31/AN01			
63	P30/AN00]		
64	AVss		A/D power supply pin (GND)	

■ I/O CIRCUIT TYPE

Туре	Circuit	Remarks
А	X1 (X1A) X0 (X0A) Standby control	 Oscillation circuit High-speed side Feedback resistance value : approx. 1 MΩ Low-speed side Feedback resistance : approx. 24 MΩ (EVA product : approx. 10 MΩ) Dumping resistance : approx. 144 kΩ (EVA product : without dumping resistance)
В	R H	Only for input Hysteresis input only for MASK product With pull-down resistor only for MASK product
B'		Hysteresis input only for MASK product
С	Standby control External interrupt enable	CMOS output Hysteresis input
G	Pull-up control Nch Standby control	CMOS output CMOS input Hysteresis input With pull - up control
Н	Pull-up control Standby control	CMOS output Hysteresis input With pull - up control



■ HANDLING DEVICES

Preventing Latchup

Care must be taken to ensure that maximum voltage ratings are not exceeded when they are used.

Latchup may occur on CMOS ICs if voltage higher than Vcc or lower than Vss is applied to input and output pins other than medium- and high-withstand voltage pins or if higher than the rating voltage is applied between Vcc and Vss.

When latchup occurs, power supply current increases rapidly and might thermally damage elements.

Also, take care to prevent the analog power supply voltage (AVcc, AVR) and analog input voltage from exceeding the digital power supply voltage (Vcc) when the analog system power supply is turned on or off.

• Stable Supply Voltage

Supply voltage should be stabilized.

A sudden change in power-supply voltage may cause a malfunction even within the guaranteed operating range of the Vcc power-supply voltage.

For stabilization, in principle, keep the variation in Vcc ripple (p-p value) in a commercial frequency range (50 Hz to 60 Hz) not to exceed 10% of the Vcc value and suppress the voltage variation so that the transient variation rate does not exceed 0.1 V/ms during a momentary change such as when the power supply is switched.

• Treatment of Unused Input Pin

An unused input pin may cause a malfunction if it is left open. It should be connected to a pull-up or pull-down resistor.

• Treatment of Power Supply Pins on A/D Converter

Connect to be AVcc = Vcc and AVss = AVR = Vss even if the A/D converter is not in use.

Precautions for Use of External Clock

Even when an external clock is used, oscillation stabilization wait time is required for power-on reset, wake-up from subclock mode or stop mode.

• Precaution against Noise to the External Reset Pin (RST)

An input of a reset pulse below the specified level to the external reset pin (\overline{RST}) may cause malfunctions. Be sure not to allow an input of a reset pulse below the specified level to the external reset pin (\overline{RST}) .

■ PROGRAMMING FLASH MICROCONTROLLERS USING PARALLEL PROGRAMMER

• Supported Parallel Programmers and Adapters

The following table lists supported parallel programmers and adapters.

Package	Applicable adapter model	Parallel programmers
FPT-64P-M03	TEF110-108F35AP	AF9708 (Ver 02.35G or more) AF9709/B (Ver 02.35G or more)
FPT-64P-M09	TEF110-108F36AP	AF9723+AF9834 (Ver 02.08E or more)

Notes: • Set all of the J1 to J3 switches on the adapter to "95F108".

• For information on applicable adapter models and parallel programmers, contact the following: Flash Support Group, Inc. TEL: 053-428-8380

• Sector Configuration

The individual sectors of flash memory correspond to addresses used for CPU access and programming by the parallel programmer as follows:

FLASH memory	CPU address	Writer address*	
SA1 (4 Kbytes)	1000н	7 <u>10</u> 00 _H	
	1FFFн	71FFFн	~
SA2 (4Kbytes)	2000н	72000н	Lower bank
- (-) /	2FFFн	72FFFн)We
SA3 (4 Kbytes)	3000н	73000н]]]
(3FFFн	73FFFн	
SA4 (16 Kbytes)	4000н	74000н	
, ,	7FFF _H	77FFFн	
SA5 (16 Kbytes)	8000н	78000н	
	BFFFH	7BFFF н	
SA6 (4 Kbytes)	С000н — —	7 <u>С</u> 000 _н	ᆂ
	CFFFH	7CFFFн	ba
SA7 (4 Kbytes)		7D000H	Upper bank
- (DFFFH	7DFFF⊦	
SA8 (4 Kbytes)	Е000н	7E000н	
21.12 (1.1.2)(20)	EFFFH	7EFFF _H	
SA9 (4 Kbytes)	F000 _H	7F000н	
2.15 (1.15)100)	<u>FFFF</u> H	7FFFF _H	

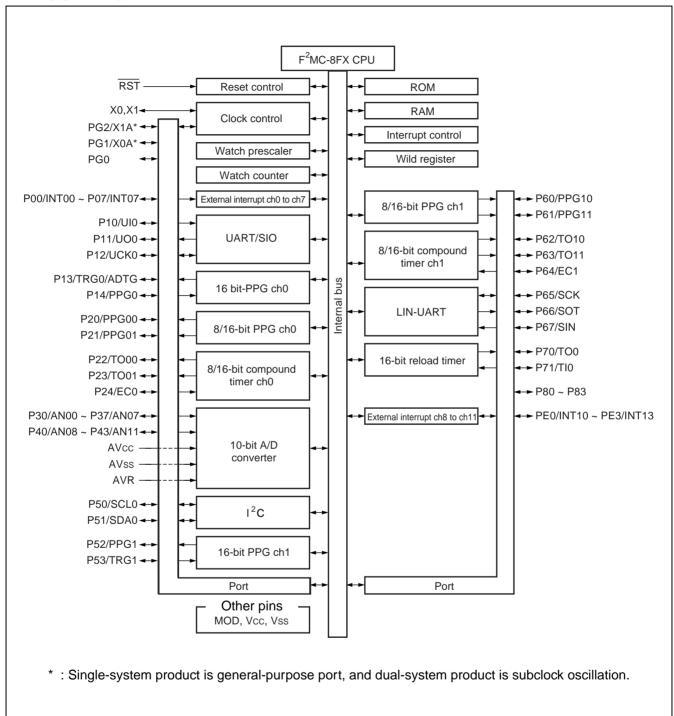
^{*:} Programmer addresses are equivalent to CPU addresses, used when the parallel programmer programs data into flash memory.

These programmer addresses are used for the parallel programmer to program or erase data in flash memory.

• Programming Method

- 1) Set the type code of the parallel programmer to 17226.
- 2) Load program data to programmer addresses 71000H to 7FFFFH.
- 3) Programmed by parallel programmer

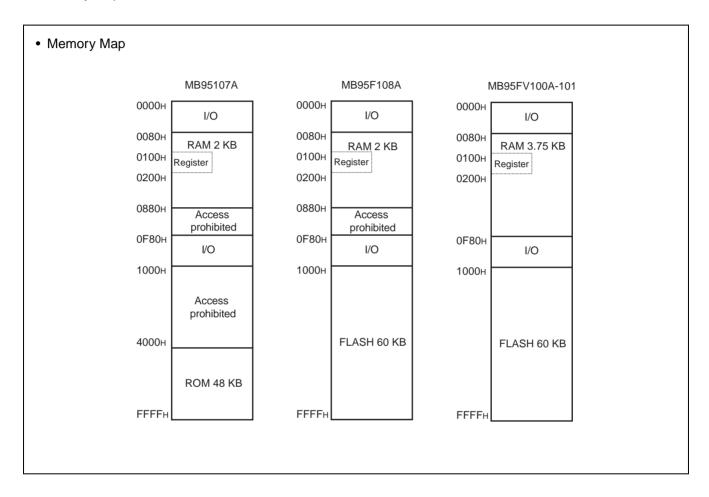
■ BLOCK DIAGRAM



■ CPU CORE

1. Memory space

Memory space of the MB95100A series is 64 Kbytes and consists of I/O area, data area, and program area. The memory space includes special - purpose areas such as the general - purpose registers and vector table. Memory map of the MB95100A series is shown in below.



2. Register

The MB95100A series has two types of registers; dedicated registers in the CPU and general-purpose registers in the memory. The dedicated registers are as follows:

Program counter (PC) : A 16-bit register to indicate locations where instructions are stored.

Accumulator (A) : A 16-bit register for temporary storage of arithmetic operations. In the case of

an 8-bit data processing instruction, the lower one byte is used.

Temporary accumulator (T) : A 16-bit register which performs arithmetic operations with the accumulator.

In the case of an 8-bit data processing instruction, the lower one byte is used.

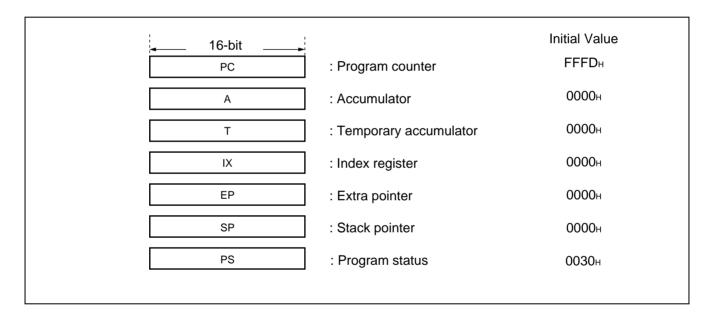
Index register (IX) : A 16-bit register for index modification

Extra pointer (EP) : A 16-bit pointer to point to a memory address.

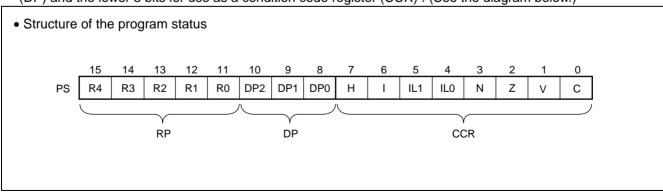
Stack pointer (SP) : A 16-bit register to indicate a stack area.

Program status (PS) : A 16-bit register for storing a register bank pointer, a direct bank pointer, and

a condition code register



The PS can further be divided into higher 8 bits for use as a register bank pointer (RP) and a direct bank pointer (DP) and the lower 8 bits for use as a condition code register (CCR). (See the diagram below.)



The RP indicates the address of the register bank currently being used. The relationship between the content of RP and the real address conforms to the conversion rule illustrated below:

• Rule for Conversion of Actual Addresses in the General-purpose Register Area RP upper OP code lower "1" R4 R3 R2 R1 R0 b2 b1 b0 ¥ ¥ ¥ ¥ ¥ ¥ ***** Generated address A15 A14 A13 A12 A11 **A8** АЗ A2 Α1 A0 A10 A9 Α7 A6 A5 A4

The DP specifies the area for mapping instructions (16 different instructions such as MOV A, dir) using direct addresses to 0080H to 00FFH.

Direct bank pointer (DP2 to DP0)	Specified address area	Mapping area
Don't care	0000н to 007Fн	0000н to 007Fн (without mapping)
000 _B (initial value)		0080н to 00FFн (without mapping)
001в		0100н to 017Fн
010в		0180н to 01FFн
011в	0000 +- 0055	0200н to 027Fн
100в	— 0080н to 00FFн	0280н to 02FFн
101в		0300н to 037Fн
110в		0380н to 03FFн
111в		0400н to 047Fн

The CCR consists of the bits indicating arithmetic operation results or transfer data contents and the bits that control CPU operations at interrupt.

: Set to "1" when a carry or a borrow from bit 3 to bit 4 occurs as a result of an arithmetic operation. H flag

Cleared to "0" otherwise. This flag is for decimal adjustment instructions.

: Interrupt is enabled when this flag is set to "1". Interrupt is disabled when this flag is set to "0". I flag

The flag is set to "0" when reset.

IL1, IL0 : Indicates the level of the interrupt currently enabled. Processes an interrupt only if its request level is higher than the value indicated by this bit.

IL1	IL0	Interrupt level	Priority
0	0	0	High
0	1	1	↑
1	0	2	_
1	1	3	Low = no interruption

: Set to "1" if the MSB is set to "1" as the result of an arithmetic operation. Cleared to "0" when the N flag bit is set to "0".

: Set to "1" when an arithmetic operation results in 0. Cleared to "0" otherwise.

: Set to "1" if the complement on 2 overflows as a result of an arithmetic operation. Cleared to "0" V flag otherwise.

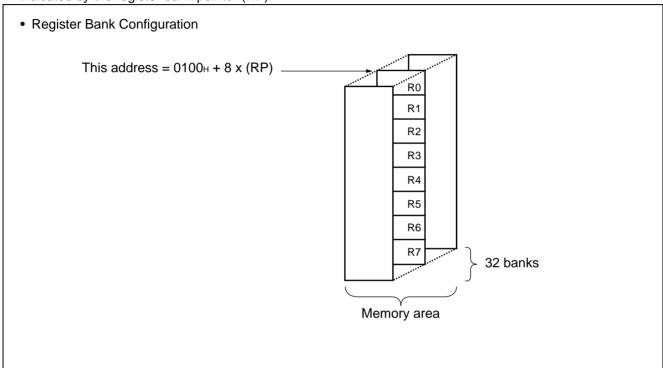
: Set to "1" when a carry or a borrow from bit 7 occurs as a result of an arithmetic operation. Cleared C flag

to "0" otherwise. Set to the shift-out vallue in the case of a shift instruction.

The following general-purpose registers are provided:

General-purpose registers: 8-bit data storage registers

The general-purpose registers are 8 bits and located in the register banks on the memory. One bank contains eight registers. Up to a total of 32 banks can be used on the MB95100A series. The bank currently in use is indicated by the register bank pointer (RP).



■ I/O MAP

Address	Register abbreviation	Register name	R/W	Initial value
0000н	PDR0	Port 0 data register	R/W	0000000В
0001н	DDR0	Port 0 direction register	R/W	00000000В
0002н	PDR1	Port 1 data register	R/W	00000000в
0003н	DDR1	Port 1 direction register	R/W	00000000в
0004н	_	(Vacancy)	_	_
0005н	WATR	Oscillation stabilization wait time setting register	R/W	11111111в
0006н	PLLC	PLL control register	R/W	00000000в
0007н	SYCC	System clock control register	R/W	1010X011в
0008н	STBC	Standby control register	R/W	00000000в
0009н	RSRR	Reset source register	R	XXXXXXXX
000Ан	TBTC	Timebase timer control register	R/W	0000000в
000Вн	WPCR	Watch prescaler control register	R/W	0000000
000Сн	WDTC	Watchdog timer control register	R/W	0000000
000Дн	_	(Vacancy)	_	_
000Ен	PDR2	Port 2 data register	R/W	00000000в
000Fн	DDR2	Port 2 direction register	R/W	0000000В
0010н	PDR3	Port 3 data register	R/W	0000000
0011н	DDR3	Port 3 direction register	R/W	00000000В
0012н	PDR4	Port 4 data register	R/W	00000000в
0013н	DDR4	Port 4 direction register	R/W	00000000В
0014н	PDR5	Port 5 data register	R/W	00000000в
0015н	DDR5	Port 5 direction register	R/W	00000000в
0016н	PDR6	Port 6 data register	R/W	00000000в
0017н	DDR6	Port 6 direction register	R/W	0000000В
0018н	PDR7	Port 7 data register	R/W	0000000В
0019н	DDR7	Port 7 direction register	R/W	0000000В
001Ан	PDR8	Port 8 data register	R/W	0000000В
001Вн	DDR8	Port 8 direction register	R/W	0000000В
001Сн to 0025н	_	(Vacancy)	_	_
0026н	PDRE	Port E data register	R/W	0000000В
0027н	DDRE	Port E direction register	R/W	0000000В
0028н		(Magazan)		
0029н	-	(Vacancy)	_	_
002Ан	PDRG	Port G data register	R/W	0000000в

Address	Register abbreviation	Register name	R/W	Initial value
002Вн	DDRG	Port G direction register	R/W	0000000В
002Сн	_	(Vacancy)	_	_
002Dн	PUL1	Port 1 pull - up register	R/W	0000000В
002Ен	PUL2	Port 2 pull - up register	R/W	0000000В
002Fн	PUL3	Port 3 pull - up register	R/W	0000000В
0030н	PUL4	Port 4 pull - up register	R/W	0000000В
0031н	PUL5	Port 5 pull - up register	R/W	0000000В
0032н	PUL7	Port 7 pull - up register	R/W	0000000В
0033н		(Vacancy)	_	_
0034н	PULE	Port E pull - up register	R/W	0000000В
0035н	PULG	Port G pull - up register	R/W	0000000В
0036н	T01CR1	8/16-bit compound timer 01 control status register 1 ch0	R/W	0000000В
0037н	T00CR1	8/16-bit compound timer 00 control status register 1 ch0	R/W	0000000В
0038н	T11CR1	8/16-bit compound timer 11 control status register 1 ch1	R/W	0000000В
0039н	T10CR1	8/16-bit compound timer 10 control status register 1 ch1	R/W	0000000В
003Ан	PC01	8/16-bit PPG1 control register ch0	R/W	0000000В
003Вн	PC00	8/16-bit PPG0 control register ch0	R/W	0000000В
003Сн	PC11	8/16-bit PPG1 control register ch1	R/W	0000000В
003Dн	PC10	8/16-bit PPG0 control register ch1	R/W	0000000В
003Ен	TMCSRH0	16-bit reload timer control status register (Upper byte) ch0	R/W	0000000В
003Fн	TMCSRL0	16-bit reload timer control status register (Lower byte) ch0	R/W	0000000В
0040н		(Macana)		
0041н		(Vacancy)	_	_
0042н	PCNTH0	16-bit PPG control status register (Upper byte) ch0	R/W	0000000В
0043н	PCNTL0	16-bit PPG control status register (Lower byte) ch0	R/W	0000000В
0044н	PCNTH1	16-bit PPG control status register (Upper byte) ch1	R/W	0000000В
0045н	PCNTL1	16-bit PPG control status register (Lower byte) ch1	R/W	0000000В
0046н		(Vacanav)		
0047н		(Vacancy)	_	_
0048н	EIC00	External interrupt circuit control register ch0/1	R/W	0000000В
0049н	EIC10	External interrupt circuit control register ch2/3	R/W	0000000В
004Ан	EIC20	External interrupt circuit control register ch4/5	R/W	0000000В
004Вн	EIC30	External interrupt circuit control register ch6/7	R/W	0000000В
004Сн	EIC01	External interrupt circuit control register ch8/9	R/W	0000000В
004Dн	EIC11	External interrupt circuit control register ch10/11	R/W	0000000В

Address	Register abbreviation	R/W	Initial value	
004Ен				
004Fн	_	(Vacancy)	_	
0050н	SCR	LIN-UART serial control register	R/W	0000000В
0051н	SMR	LIN-UART serial mode register	R/W	0000000В
0052н	SSR	LIN-UARTserial status register	R/W	00001000в
0053н	RDR/TDR	LIN-UART reception/transmission data register	R/W	0000000В
0054н	ESCR	LIN-UART extended status control register	R/W	00000100в
0055н	ECCR	LIN-UART extended communication control register	R/W	000000XXB
0056н	SMC10	UART/SIO serial mode control register 1 ch0	R/W	0000000В
0057н	SMC20	UART/SIO serial mode control register 2 ch0	R/W	00100000в
0058н	SSR0	UART/SIO serial status register ch0	R/W	0000001в
0059н	TDR0	UART/SIO serial output data register ch0	R/W	0000000В
005Ан	RDR0	UART/SIO serial input data register ch0	R	0000000В
005Вн to 005Fн	_	(Vacancy)	_	_
0060н	IBCR00	I ² C bus control register 0 ch0	R/W	0000000В
0061н	IBCR10	I ² C bus control register 1 ch0	R/W	0000000в
0062н	IBSR0	I ² C bus status register ch0	R	0000000в
0063н	IDDR0	I ² C data register ch0	R/W	0000000в
0064н	IAAR0	I ² C address register ch0	R/W	0000000в
0065н	ICCR0	I ² C clock control register ch0	R/W	0000000в
0066н to 006Вн	_	(Vacancy)	_	_
006Сн	ADC1	A/D control register 1	R/W	0000000в
006Dн	ADC2	A/D control register 2	R/W	0000000в
006Ен	ADDH	A/D data register (Upper byte)	R/W	0000000в
006Fн	ADDL	A/D data register (Lower byte)	R/W	0000000в
0070н	WCSR	Watch counter status register	R/W	0000000в
0071н	_	(Vacancy)	_	_
0072н	FSR	FLASH memory status register	R/W	000Х0000в
0073н	SWRE0	FLASH memory sector writing control register 0	R/W	0000000В
0074н	SWRE1	FLASH memory sector writing control register 1	R/W	0000000В
0075н	_	(Vacancy)	_	_
0076н	WREN	Wild register address compare enable register	R/W	0000000В
0077н	WROR	Wild register data test setting register	R/W	0000000В

Address	Register abbreviation	Register name	R/W	Initial value
0078н	_	(Mirror of register bank pointer (RP) and direct bank pointer (DP))	_	_
0079н	ILR0	Interrupt level setting register 0	R/W	11111111в
007Ан	ILR1	Interrupt level setting register 1	R/W	11111111в
007Вн	ILR2	Interrupt level setting register 2	R/W	11111111 _B
007Сн	ILR3	Interrupt level setting register 3	R/W	11111111в
007Dн	ILR4	Interrupt level setting register 4	R/W	11111111в
007Ен	ILR5	Interrupt level setting register 5	R/W	11111111в
007Fн	_	(Vacancy)	_	_
0F80н	WRARH0	Wild register address setting register (Upper byte) ch0	R/W	0000000в
0F81н	WRARL0	Wild register address setting register (Lower byte) ch0	R/W	0000000В
0F82н	WRDR0	Wild register data setting register ch0	R/W	0000000В
0F83н	WRARH1	Wild register address setting register (Upper byte) ch1	R/W	0000000В
0F84н	WRARL1	Wild register address setting register (Lower byte) ch1	R/W	0000000В
0F85н	WRDR1	Wild register data setting register ch1	R/W	0000000В
0F86н	WRARH2	Wild register address setting register (Upper byte) ch2	R/W	0000000В
0F87н	WRARL2	Wild register address setting register (Lower byte) ch2	R/W	0000000В
0F88н	WRDR2	Wild register data setting register ch2	R/W	0000000В
0F89н to 0F91н	_	(Vacancy)	_	_
0F92н	T01CR0	8/16-bit compound timer 01 control status register 0 ch0	R/W	0000000В
0F93н	T00CR0	8/16-bit compound timer 00 control status register 0 ch0	R/W	0000000В
0F94н	T01DR	8/16-bit compound timer 01 data register ch0	R/W	0000000В
0F95н	T00DR	8/16-bit compound timer 00 data register ch0	R/W	0000000В
0F96н	TMCR0	8/16-bit compound timer 00/01 timer mode control register ch0	R/W	00000000в
0F97н	T11CR0	8/16-bit compound timer 11 control status register 0 ch1	R/W	0000000В
0F98н	T10CR0	8/16-bit compound timer 10 control status register 0 ch1	R/W	0000000В
0F99н	T11DR	8/16-bit compound timer 11 data register ch1	R/W	0000000В
0F9Ан	T10DR	8/16-bit compound timer 10 data register ch1	R/W	0000000В
0F9Вн	TMCR1	8/16-bit compound timer 10/11 timer mode control register ch1	R/W	00000000в
0F9Cн	PPS01	8/16-bit PPG1 cycle setting buffer register ch0	R/W	11111111в
0F9Dн	PPS00	8/16-bit PPG0 cycle setting buffer register ch0	R/W	11111111в
0F9Eн	PDS01	8/16-bit PPG1 duty setting buffer register ch0	R/W	11111111в
0F9Fн	PDS00	8/16-bit PPG0 duty setting buffer register ch0	R/W	11111111в

Address	Register abbreviation	Register name	R/W	Initial value
0FА0н	PPS11	8/16-bit PPG1 cycle setting buffer register ch1	R/W	11111111в
0FA1н	PPS10	8/16-bit PPG0 cycle setting buffer register ch1	R/W	11111111В
0FA2н	PDS11	8/16-bit PPG1 duty setting buffer register ch1	R/W	11111111в
0FАЗн	PDS10	8/16-bit PPG0 duty setting buffer register ch1	R/W	11111111в
0FA4н	PPGS	8/16-bit PPG start register	R/W	0000000В
0FА5н	REVC	8/16-bit PPG output inversion register	R/W	0000000В
0FA6н	TMRH0/ TMRLRH0	16-bit timer register (Upper byte) ch0/ 16-bit reload register (Upper byte) ch0	R/W	00000000в
0FA7н	TMRL0/ TMRLRL0	16-bit timer register (Lower byte) ch0/ 16-bit reload register (Lower byte) ch0	R/W	00000000в
0FA8н		(Vacancy)		
0FА9н		(vacancy)		
0ҒААн	PDCRH0	16-bit PPG down counter register (Upper byte) ch0	R	0000000В
0ҒАВн	PDCRL0	16-bit PPG down counter register (Lower byte) ch0	R	0000000В
0FАСн	PCSRH0	16-bit PPG cycle setting buffer register (Upper byte) ch0	R/W	11111111в
0FADн	PCSRL0	16-bit PPG cycle setting buffer register (Lower byte) ch0	R/W	11111111В
0FAEн	PDUTH0	16-bit PPG duty setting buffer register (Upper byte) ch0	R/W	11111111в
0FAFн	PDUTL0	16-bit PPG duty setting buffer register (Lower byte) ch0	R/W	11111111в
0FB0н	PDCRH1	16-bit PPG down counter register (Upper byte) ch1	R	0000000В
0FB1н	PDCRL1	16-bit PPG down counter register (Lower byte) ch1	R	0000000В
0FB2н	PCSRH1	16-bit PPG cycle setting buffer register (Upper byte) ch1	R/W	11111111в
0FB3н	PCSRL1	16-bit PPG cycle setting buffer register (Lower byte) ch1	R/W	11111111В
0FB4н	PDUTH1	16-bit PPG duty setting buffer registe (Upper byte) ch1	R/W	11111111в
0FB5н	PDUTL1	16-bit PPG duty setting buffer register (Lower byte) ch1	R/W	11111111в
0FB6н to 0FBBн	_	(Vacancy)	_	_
0FBCн	BGR1	LIN-UART baud rate generator register 1	R/W	0000000В
0FBDн	BGR0	LIN-UART baud rate generator register 0	R/W	0000000В
0FBЕн	PSSR0	UART/SIO prescaler selection register ch0	R/W	0000000В
0FBFн	BRSR0	UART/SIO baud rate setting register ch0	R/W	0000000В
0FC0н 0FC1н	_	(Vacancy)		_
0FC2н	AIDRH	A/D input disable register (Upper byte)	R/W	0000000
0FС3н	AIDRL	A/D input disable register (Lower byte)	R/W	00000000
0FC4н to 0FE2н	_	(Vacancy)	_	_

(Continued)

Address	Register abbreviation	Register name	R/W	Initial value
0FE3н	WCDR	Watch counter data register	R/W	00111111в
0FE4н to 0FEDн	_	(Vacancy)	_	_
0FEEн	ILSR	Input level select register	R/W	0000000В
0FEF _H	WICR	Interrupt pin control register	R/W	01000000в
0FF0н to 0FFFн	_	(Vacancy)	_	_

• Read/write access symbols

R/W : Readable and Writable

R : Read only W : Write only

• Initial value symbols

0 : The initial value of this bit is "0".1 : The initial value of this bit is "1".

X : The initial value of this bit is undefined.

■ INTERRUPT SOURCE TABLE

	Interrupt	Vector tab	le address	Bit name of	Same level	
Interrupt source	request number			interrupt level setting register	priority order (atsimultaneous occurrence)	
External interrupt ch0	IRQ0	FFFA _H	FFFB⊦ı	L00 [1 : 0]	High	
External interrupt ch4	IRQU	ГГГАН	ГГГОН	L00 [1 . 0]	A	
External interrupt ch1	IRQ1	FFF8 _H	FFF9 _H	L01 [1 : 0]	↑	
External interrupt ch5	IKQI	ГГГОН	гггэн	LOTET. Of		
External interrupt ch2	IRQ2	ГГГС	ГГГ7.	1.02.[4 . 0]		
External interrupt ch6	IRQZ	FFF6 _H	FFF7 _H	L02 [1 : 0]		
External interrupt ch3	IDO2	FFF4		1 02 [4 . 0]		
External interrupt ch7	IRQ3	FFF4 _H	FFF5⊦	L03 [1 : 0]		
UART/SIO ch0	IRQ4	FFF2 _H	FFF3⊦	L04 [1 : 0]		
8/16-bit compound timer ch0 (Lower)	IRQ5	FFF0 _H	FFF1 _H	L05 [1 : 0]		
8/16-bit compound timer ch0 (Upper)	IRQ6	FFEEH	FFEFH	L06 [1 : 0]		
LIN-UART (reception)	IRQ7	FFECH	FFEDH	L07 [1:0]		
LIN-UART (transmission)	IRQ8	FFEAH	FFEBH	L08 [1 : 0]		
8/16-bit PPG ch1 (Lower)	IRQ9	FFE8 _H	FFE9 _H	L09 [1 : 0]		
8/16-bit PPG ch1 (Upper)	IRQ10	FFE6 _H	FFE7 _H	L10 [1:0]		
16-bit reload timer ch0	IRQ11	FFE4 _H	FFE5 _H	L11 [1 : 0]		
8/16-bit PPG ch0 (Upper)	IRQ12	FFE2 _H	FFE3 _H	L12 [1 : 0]		
8/16-bit PPG ch0 (Lower)	IRQ13	FFE0 _H	FFE1 _H	L13 [1 : 0]		
8/16-bit compound timer ch1 (Upper)	IRQ14	FFDE _H	FFDFн	L14 [1 : 0]		
16-bit PPG ch0	IRQ15	FFDCH	FFDDH	L15 [1 : 0]		
I ² C ch0	IRQ16	FFDA _H	FFDB⊦	L16 [1 : 0]		
16-bit PPG ch1	IRQ17	FFD8 _H	FFD9⊦	L17 [1:0]		
10-bit A/D converter	IRQ18	FFD6 _H	FFD7 _H	L18 [1 : 0]		
Timebase timer	IRQ19	FFD4 _H	FFD5 _H	L19 [1 : 0]		
Watch timer/counter	IRQ20	FFD2 _H	FFD3 _H	L20 [1 : 0]		
External interrupt ch8						
External interrupt ch9	IDO24	EEDO	EED4	1 24 [4 . 0]		
External interrupt ch10	IRQ21	FFD0 _H	FFD1 _H	L21 [1 : 0]		
External interrupt ch11						
8/16-bit compound timer ch1 (Lower)	IRQ22	FFCEH	FFCFH	L22 [1 : 0]	▼	
FLASH	IRQ23	FFCCH	FFCDH	L23 [1 : 0]	Low	

■ ELECTRICAL CHARACTERISTICS

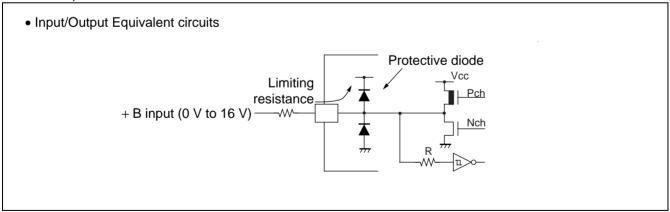
1. Absolute Maximum Ratings

Doromotor	Cumbal	Rating		l lmi4	Domasko		
Parameter	Symbol	Min	Max	Unit	Remarks		
Power supply voltage*1	Vcc AVcc	Vss - 0.3	Vss + 4.0	V	*2		
	AVR	Vss - 0.3	Vss + 4.0	-	*2		
least valtage*1	Vıı	Vss - 0.3	Vss + 4.0	V	Other than P50, P51, P80 to P83*3		
Input voltage*1	Vı2	Vss - 0.3	Vss + 6.0	V	P50, P51, P80 to P83		
Output voltage*1	Vo	Vss - 0.3	Vss + 4.0	V	*3		
Maximum clamp current	CLAMP	- 2.0	+ 2.0	mA	Applicable to pins*4		
Total maximum clamp current	$\Sigma I_CLAMP $	_	20	mA	Applicable to pins*4		
"L" level maximum	lol1		15	mΛ	Other than P00 to P07		
output current	OL2		15	mA	P00 to P07		
"L" level average	lolav1		4		Other than P00 to P07 Average output current = operating current × operating ratio (1 pin)		
current	lolav2		12	- mA	P00 to P07 Average output current = operating current × operating ratio (1 pin)		
"L" level total maximum output current	ΣΙοι	_	100	mA			
"L" level total average output current	ΣΙοιαν	_	50	mA	Total average output current = operating current × operating ratio (Total of pins)		
"H" level maximum	І он1		– 15	mΛ	Other than P00 to P07		
output current	І ОН2	_	– 15	mA	P00 to P07		
"H" level average	Iонаv1		- 4	mA	Other than P00 to P07 Average output current = operating current × operating ratio (1 pin)		
current	Іонаv2	IOHAV2		IIIA	P00 to P07 Average output current = operating current × operating ratio (1 pin)		
"H" level total maximum output current	Σ Іон	_	- 100	mA			
"H" level total average output current	ΣΙομαν	_	- 50	mA	Total average output current = operating current × operating ratio (Total of pins)		

(Continued)

Parameter	Symbol	Rat	ing	Unit	Remarks
raiametei	Syllibol	Min	Max	Oilit	Kemarks
Power consumption	Pd	_	320	mW	
Operating temperature	TA	- 40	+ 85	°C	Other than MB95FV100A-101
Storage temperature	Tstg	– 55	+ 150	°C	

- *1 : The parameter is based on AVss = Vss = 0.0 V.
- *2 : Apply equal potential to AVcc and Vcc. AVR should not exceed AVcc + 0.3 V.
- *3: V_{I1} and Vo should not exceed V_{CC} + 0.3 V. V_{I1} must not exceed the rating voltage. However, if the maximum current to/from an input is limited by some means with external components, the I_{CLAMP} rating supersedes the V_{I1} rating.
- *4 : Applicable to pins : P00 to P07, P10 to P14, P20 to P24, P30 to P37, P40 to P43, P52, P53, P70, P71, PE0 to PE3, PG0
 - Use within recommended operating conditions.
 - Use at DC voltage (current).
 - The + B signal should always be applied a limiting resistance placed between the + B signal and the microcontroller.
 - The value of the limiting resistance should be set so that when the + B signal is applied the input current to the microcontroller pin does not exceed rated values, either instantaneously or for prolonged periods.
 - Note that when the microcontroller drive current is low, such as in the power saving modes, the +B input
 potential may pass through the protective diode and increase the potential at the VCC pin, and this may
 affect other devices.
 - Note that if the + B signal is inputted when the microcontroller power supply is off (not fixed at 0 V), the power supply is provided from the pins, so that incomplete operation may result.
 - Note that if the + B input is applied during power-on, the power supply is provided from the pins and the resulting power supply voltage may not be sufficient to operate the power-on reset.
 - Care must be taken not to leave the + B input pin open.
 - Sample recommended circuits :



WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

2. Recommended Operating Conditions

(AVss = Vss = 0.0 V)

Parameter	Symbol Value		lue	Unit	Remarks
Farameter	Syllibol	Min	Max	Ullit	Remarks
		1.8*1	3.3*2		At normal operating, FLASH product, $T_A = -10$ °C to +85 °C
		1.8*1	3.6		At normal operating, MASK product, T _A = -10 °C to +85 °C
		2.0*1	3.3*2		At normal operating, FLASH product, T _A = -40 °C to +85 °C
Power supply voltage	Vcc, AVcc	2.0*1	3.6	V	At normal operating, MASK product, T _A = -40 °C to +85 °C
		2.6	3.6		MB95FV100A-101
		1.5	3.3*2		Retain status of stop operation, FLASH product
		1.5	3.6		Retain status of stop operation, MASK product
A/D converter reference input voltage	AVR	1.8	AVcc		
Operating temperature	Та	- 40	+ 85	°C	Other than MB95FV100A-101

^{*1:} The values vary with the operating frequency.

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

> Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

> No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their FUJITSU representatives beforehand.

^{*2:} Consult Fujitsu separately for a guarantee of a maximum value of 3.6 V.

3. DC Characteristics

 $(Vcc = AVcc = 3.3 \text{ V}, AVss = Vss = 0.0 \text{ V}, T_A = -40 ^{\circ}C \text{ to } +85 ^{\circ}C \text{ [MB95FV100A-101 is } T_A = +25 ^{\circ}C])$

Danama atau	Sym-	Dia nome	Condi-		Value		11:4	Damania								
Parameter	bol	Pin name	tions	Min	Тур	Max	Unit	Remarks								
	V _{IH1}	P10, P67	*1	0.7 Vcc		Vcc+0.3	V	At selecting of CMOS input level (hysteresis input)								
	V _{IH2}	P50, P51	*1	0.7 Vcc	_	Vss + 5.5	V	At selecting of CMOS input level (hysteresis input)								
"H" level input voltage	V _{IHS1}	P00 to P07, P10 to P14, P20 to P24, P30 to P37, P40 to P43, P52, P53, P60 to P67, P70, P71, PE0 to PE3, PG0, PG1*2, PG2*2	*1	0.8 Vcc	_	Vcc+0.3	>	Hysteresis input								
	V _{IHS2}	P50, P51, P80 to P83	*1	0.8 Vcc		Vss + 5.5	V	Hysteresis input								
	Vun	RST, MOD	_	0.7 Vcc		Vcc + 0.3	V	CMOS input (FLASH product)								
	V _{ІНМ}	VIHM	VIHM	VIHM	VIHM	VIHM	VIHM	VIHM	VIHM	K31, MOD	_	0.8 Vcc		Vcc + 0.3	V	Hysteresis input (MASK product)
	VıL	P10, P50, P51, P67	*1	Vss - 0.3		0.3 Vcc	V	At selecting of CMOS input level (hysteresis input)								
"L" level input voltage	VILS	P00 to P07, P10 to P14, P20 to P24, P30 to P37, P40 to P43, P50 to P53, P60 to P67, P70, P71, P80 to P83, PE0 to PE3, PG0, PG1*2, PG2*2	*1	Vss - 0.3	_	0.2 Vcc	٧	Hysteresis input								
	VILM	VILM	VILM	VILM	VILM	RST, MOD	_	Vss - 0.3		0.3 Vcc	V	CMOS input (FLASH product)				
						VILM	VILM	VILM	VILM	IKO1, MOD		Vss - 0.3	_	0.2 Vcc	٧	Hysteresis input (MASK product)
Open-drain output application voltage	VD	P50, P51, P80 to P83	_	Vss - 0.3	_	Vss + 5.5	٧									
"H" level output	Vон1	Output pin other than P00 to P07	Iон = - 4.0 mA	2.4	_	_	V	MB95FV100A-101 a conditional : IoH = -2.0 mA								
voltage	V _{OH2}	P00 to P07	I _{OH} = - 8.0 mA	2.4	_	_	V	MB95FV100A-101 a conditional : IoH = -5.0 mA								

(Vcc = AVcc = 3.3 V, AVss = Vss = 0.0 V, $T_A = -40$ °C to +85 °C [MB95FV100A-101 is $T_A = +25$ °C])

Downwater	Sym	Din nome	Conditions		Value		I Imia	Domonto	
Parameter	bol	Pin name	name Conditions		Тур	Max	Unit	Remarks	
"L" level output	V _{OL1}	Output pin other than P00 to P07	IoL = 4.0 mA		_	0.4	V	MB95FV100A-101 a conditional : IoL = 3.0 mA	
voltage	V _{OL2}	P00 to P07	IoL = 12 mA			0.4	V	MB95FV100A-101 a conditional : lo _L = 8.0 mA	
Input leakage current (High-Z output leakage current)	lu	Port other than P50, P51, P80 to P83	0.0 V < V ₁ < Vcc	- 5	_	+ 5	μА	When no pull-up resistor is specified	
Open-drain output leakage current	ILIOD	P50, P51, P80 to P83	0.0 V < V _I < Vss + 5.5 V	_	_	+ 5	μА		
Pull-up resistor	Rpull	P10 to P14, P20 to P24, P30 to P37, P40 to P43, P52, P53, P70, P71, PE0 to PE3, PG0, PG1*2, PG2*2	Vı = 0.0 V	25	50	100	kΩ	When specifying pull-up resistor	
Pull-down resistor	Rмор	MOD	Vı = Vcc	50	100	200	kΩ	MASK product only	
				E 00.1411		11	14	mA	FLASH product
	١.		FcH = 20 MHz fmp = 10 MHz		7.3	10	mA	MASK product	
	Icc		Main clock mode (divided by 2)	_	30	35	mA	FLASH product (at FLASH writing and erasing)	
Power supply	Iccs	Vcc (External clock	FcH = 20 MHz fmp = 10 MHz Main Sleep mode (divided by 2)		4.5	6	mA		
current*3	IccL	operation)	FcL = 32 kHz fmpl = 16 kHz Subclock mode (divided by 2), TA = +25 °C	_	25	35	μА		
	Iccis		F _{CL} = 32 kHz fmpl = 16 kHz Sub sleep mode (divided by 2) , T _A = +25 °C	—	7	15	μА		

(Continued)

 $(Vcc = AVcc = 3.3 \text{ V}, AVss = Vss = 0.0 \text{ V}, T_A = -40 ^{\circ}\text{C} \text{ to } +85 ^{\circ}\text{C} \text{ [MB95FV100A-101 is } T_A = +25 ^{\circ}\text{C]})$

Parameter	Sym- bol	Pin name	Conditions		Value		Unit	Remarks
			Conditions	Min	Тур	Max	Oilit	Remarks
Power supply current*3	Ісст		Fcl = 32 kHz	_	2	10	μΑ	FLASH product
			Watch mode Main stop mode T _A = + 25 °C	_	1	5	μА	MASK product
			F _{CH} = 4 MHz	_	10	14	mA	FLASH product
	ICCMPLL		fmp = 10 MHz Main PLL mode (multiplied by 2.5)		6.7	10	mA	MASK product
	Iccspll	Vcc (External clock operation)	$F_{CL} = 32 \text{ kHz}$ fmpl = 128 kHz Sub PLL mode (multiplied by 4) , $T_A = +25 \text{ °C}$	_	190	250	μΑ	
	Істѕ		FcH = 10 MHz Timebase timer mode TA = +25 °C		0.4	0.5	mA	
	Іссн		Sub stop mode $T_A = +25$ °C		1	5	μА	
	IA		FcH = 10 MHz At operating of A/D conversion	_	1.3	2.2	mA	
	Іан	AVcc	F _{CH} = 10 MHz At stopping A/D conversion T _A = +25 °C	_	1	5	μΑ	
Input capacitance	Cin	Other than AVcc, AVss, AVR, Vcc, Vss	_	_	5	15	pF	

^{*1:} P10, P50, P51, and P67 can switch the input level to either the CMOS input level or hysteresis input level. The switching of the input level can be set by the input level selection register (ILSR).

- Refer to "4. AC characteristics (1) Clock Timing" for Fch and Fcl.
- Refer to "4. AC characteristics (2) Source Clock/Machine Clock" for fmp and fmpl.

^{*2:} Single-clock product only

^{*3:} The power-supply current is determined by the external clock.

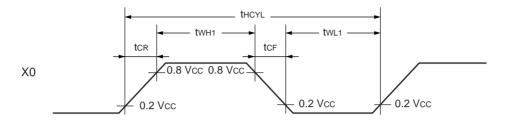
4. AC Characteristics

(1) Clock Timing

(Vcc = 3.3 V, AVss = Vss = 0.0 V, TA = -40 °C to +85 °C)

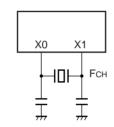
		1	1	(100			0.0	V, 1A = -40 C to +85 C)	
Parameter	Sym-	Pin	Condi- tions	Value			Unit	Remarks	
Faranietei	bol	F		Min	Тур	Max	Oilit	iveillat və	
				1	_	10	MHz	When using Main oscillation circuit	
	_	X0, X1		1		20	MHz	When using external clock	
	Fсн			3		10	MHz	Main PLL multiplied by 1	
				3		5	MHz	Main PLL multiplied by 2	
Clock frequency				3		4	MHz	Main PLL multiplied by 2.5	
Clock frequency	FcL	X0A, X1A			32.768		kHz	When using Sub oscillation circuit	
				_	32.768	_	kHz	When using sub PLL FLASH product: Vcc = 2.3 V to 3.3 V MASK product: Vcc = 2.3 V to 3.6 V	
	thcyl	X0, X1		100	_	1000	ns	When using Main oscillation circuit	
Clock cycle time				50		1000	ns	When using external clock	
	t LCYL	X0A, X1A			30.5		μs	When using Sub oscillation circuit	
Input clock pulse width	twH1	Х0	- -	10	_	_	ns	When using external clock Duty ratio is about 30% to	
Tiriput Glock puise Width	twH2	X0A			15.2		μs	70%.	
Input clock rise time and fall time	tcr tcr	X0, X0A			_	5	ns	When using external clock	

• X0 and X1 Timing and Applying Conditions

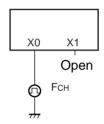


• Main Clock Applying Conditions

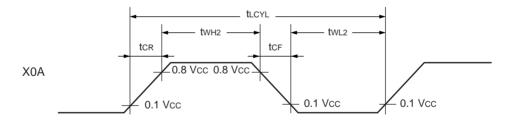
When using a crystal or ceramic oscillator



When using external clock

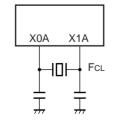


• X0A and X1A Timing and Applying Conditions

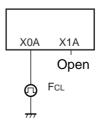


• SubClock Applying Conditions

When using a crystal or ceramic oscillator



When using external clock



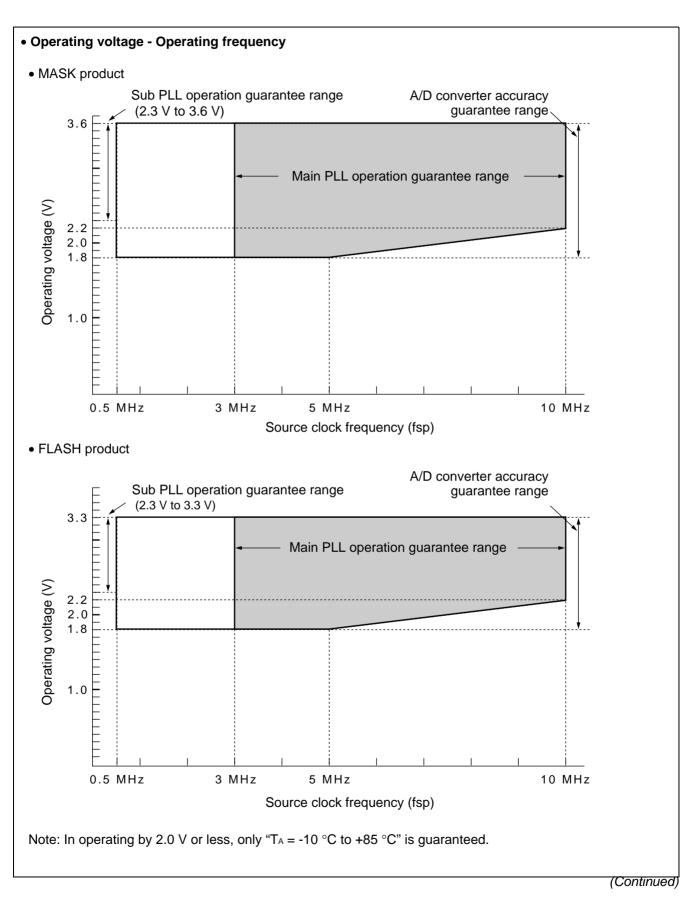
(2) Source Clock/Machine Clock

(Vcc = 3.3 V, AVss = Vss = 0.0 V, $T_A = -40 \,^{\circ}\text{C}$ to $+85 \,^{\circ}\text{C}$)

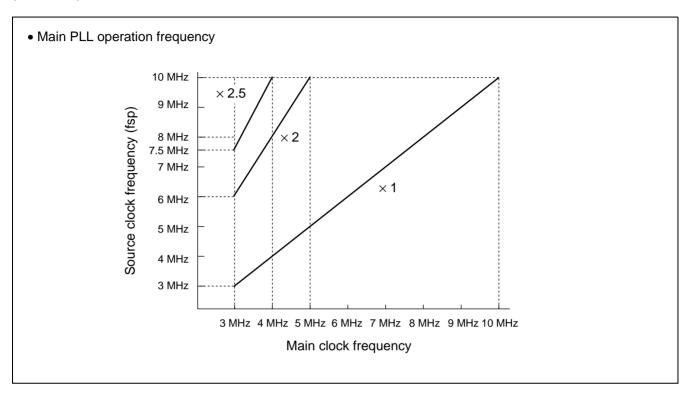
Parameter	Sym-	Pin	Value			Unit	Remarks	
Farameter	bol	name	Min	Тур	Max	Oilit	Veillai və	
Source clock*1 (Clock before setting	SCLK		100	_	2000	ns	When using Main clock Min: FcH = 10 MHz, PLL multiplied by 1 Max: FcH = 1 MHz, divided by 2	
division)	JOLK	_	7.6	_	61.0	μs	When using Subclock Min: FcL = 32 kHz, PLL multiplied by 4 Max: FcL = 32 kHz, divided by 2	
Source clock frequency	fsp	_	0.5		10.0	MHz	When using Main clock	
Source clock frequency	fspl	_	16.384	_	131.072	kHz	When using Subclock	
Machine clock*2	MCLK	_	100	_	32000	ns	When using Main clock Min: SLCK = 10 MHz, no division Max: SLCK = 0.5 MHz, divided by 16	
(Minimum instruction execution time)	MCLK		7.6	_	976.5	μs	When using Subclock Min: SLCK = 131 kHz, no division Max: SLCK = 16 kHz, divided by 16	
Machine clock frequency	fmp		0.031		10.000	MHz	When using Main clock	
Machine Clock frequency	fmpl		1.024	_	131.072	kHz	When using Subclock	

^{*1:} Clock before setting division due to machine clock division ratio selection bit (SYCC: DIV1 and DIV0). This source clock is divided by the machine clock division ratio selection bit (SYCC: DIV1 and DIV0), and it becomes the machine clock. Further, the source clock can be selected as follow.

- Main clock divided by 2
- PLL multiplication of main clock (select from 1, 2, 2.5 multiplication)
- Subclock divided by 2
- PLL multiplication of subclock (select from 2, 3, 4 multiplication)
- *2: Operation clock of the microcontroller. Machine clock can be selected as follow.
 - Source clock (no division)
 - Source clock divided by 4
 - Source clock divided by 8
 - Source clock divided by 16



(Continued)

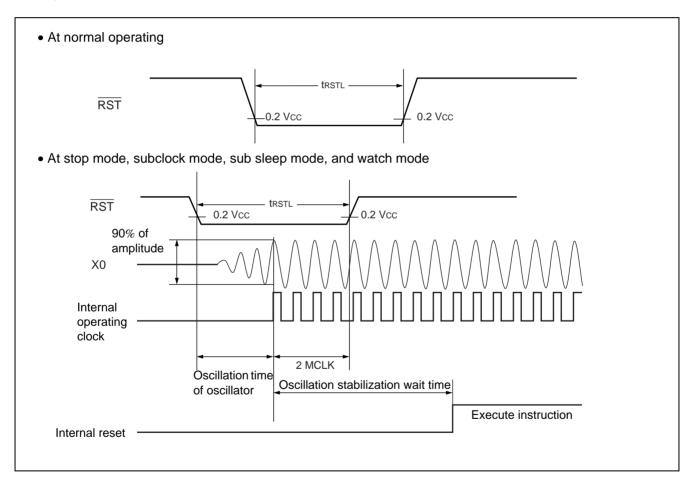


(3) Reset Timing

$$(Vcc = 3.3 \text{ V, AVss} = Vss = 0.0 \text{ V, T}_A = -40 ^{\circ}\text{C to } +85 ^{\circ}\text{C})$$

Parameter	Symbol	Value			Remarks	
Farameter	Syllibol	Min	Max		Kemarks	
RST "L" level pulse		2 MCLK*1	_	ns	At normal operating	
width	t rstl	Oscillation time of oscillator*2 + 2 MCLK*1	_	ns	At stop mode, subclock mode, sub sleep mode, and watch mode	

- *1 : Refer to " (2) Source Clock/Machine Clock" for MCLK.
- *2 : Oscillation time of oscillator is the time that the amplitude reaches 90 %. In the crystal oscillator, the oscillation time is between several ms and tens of ms. In FAR/ceramic oscillators, the oscillation time is between hundreds of μ s and several ms. In the external clock, the oscillation time is 0 ms.

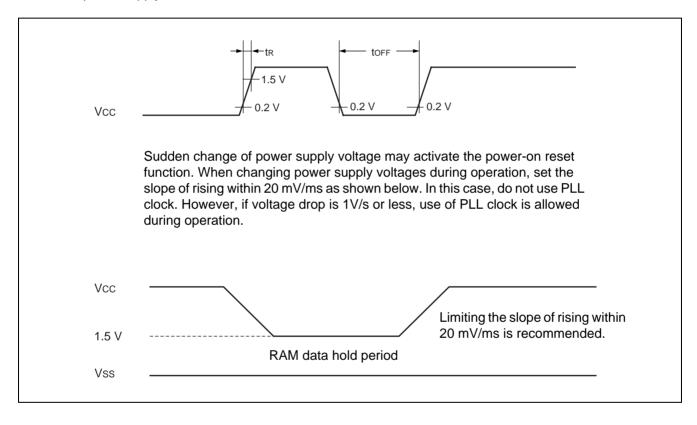


(4) Power-on Reset

(AVss = Vss = 0.0 V,
$$T_A = -40 \, ^{\circ}\text{C}$$
 to $+85 \, ^{\circ}\text{C}$)

Parameter	Symbol	Conditions	Va	lue	Unit	Remarks
raiailletei	Syllibol	Conditions	Min Max		Offic	Nemarks
Power supply rising time	t R		_	36	ms	
Power supply cutoff time	toff	_	1		ms	Due to repeated operations

Note: The power supply must be turned on within the selected oscillation stabilization time.

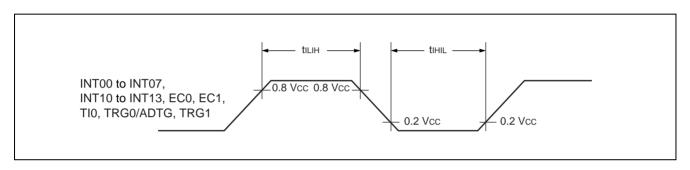


(5) Peripheral Input Timing

 $(Vcc = 3.3 \text{ V}, \text{ AVss} = \text{Vss} = 0.0 \text{ V}, \text{ T}_{A} = -40 \,^{\circ}\text{C} \text{ to } +85 \,^{\circ}\text{C})$

Parameter	Symbol	Symbol Pin name		lue	Unit	Remarks
raiailletei	Symbol	riii iidiile	Min	Max	Oilit	Remarks
Peripheral input "H" pulse width	tшн	INT00 to INT07, INT10 to INT13,	2 MCLK*	_	ns	
Peripheral input "L" pulse width	tınıl	EC0, EC1, TI0, TRG0/ADTG, TRG1	2 MCLK*	_	ns	

^{*:} Refer to "(2) Source Clock/Machine Clock" for MCLK.

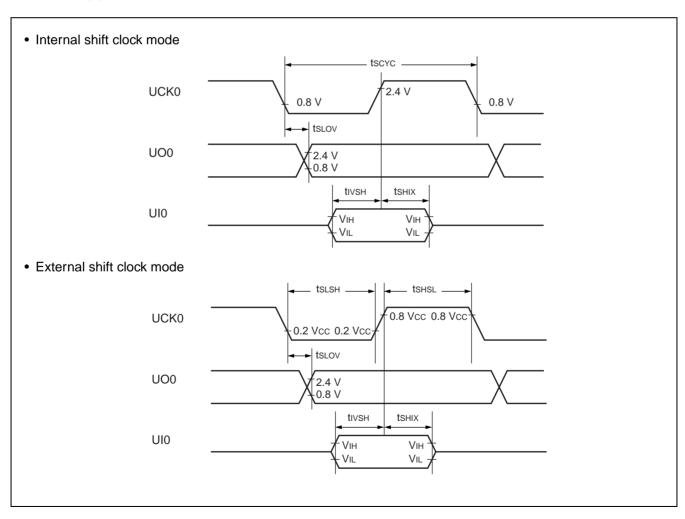


(6) UART/SIO, Serial I/O Timing

 $(Vcc = 3.3 \text{ V}, \text{ AVss} = \text{Vss} = 0.0 \text{ V}, \text{ T}_{A} = -40 \,^{\circ}\text{C to } +85 \,^{\circ}\text{C})$

Doromotor	Symbol Pin name		Canditions	Val	lue	Unit	Domarke
Parameter	Symbol	rin name	Conditions	Min	Max	Ullit	Remarks
Serial clock cycle time	tscyc	UCK0		4 MCLK*	_	ns	
$UCK\downarrow \to UO$ time	t sLov	UCK0, UO0	Internal clock	- 190	190	ns	
Valid UI → UCK ↑	tıvsн	UCK0, UI0	operation	2 MCLK*		ns	
$UCK \uparrow \to valid \; UI \; hold \; time$	t shix	UCK0, UI0		2 MCLK*		ns	
Serial clock "H" pulse width	t shsl	UCK0		4 MCLK*		ns	
Serial clock "L" pulse width	t slsh	UCK0	External	4 MCLK*		ns	
$UCK\downarrow \to UO$ time	t sLov	UCK0, UO0	clock	_	190	ns	
Valid UI → UCK ↑	t ıvsh	UCK0, UI0	operation	2 MCLK*		ns	
$UCK \uparrow \to valid \; UI \; hold \; time$	t shix	UCK0, UI0		2 MCLK*	_	ns	

^{*:} Refer to "(2) Source Clock/Machine Clock" for MCLK.



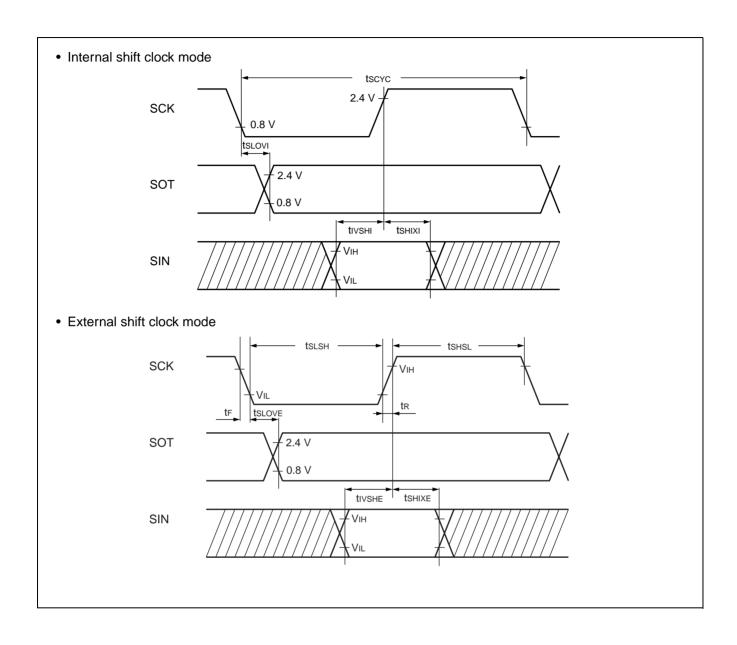
(7) LIN-UART Timing

 $\mathsf{ESCR}: \mathsf{SCES} = \mathbf{0}, \, \mathsf{ECCR}: \mathsf{SCDE} = \mathbf{0}$

(Vcc = 3.3 V, AVss = Vss = 0.0 V, $T_A = -40$ °C to +85 °C)

Doromotor	Sym-	Din nama	Canditions	Va	lue	l loit
Parameter	bol	Pin name	Conditions	Min	Max	Unit
Serial clock cycle time	tscyc	SCK		5 MCLK*		ns
SCK ↑→ SOT delay time	tslovi	SCK, SOT	Internal clock	-95	95	ns
Valid SIN→SCK↑	t ıvshı	SCK, SIN	operation output pin : C _L = 80 pF + 1 TTL	MCLK* + 190	_	ns
SCK [↑] → valid SIN hold time	t shixi	SCK, SIN		0	_	ns
Serial clock "L" pulse width	t slsh	SCK		3 MCLK* – t _R	_	ns
Serial clock "H" pulse width	t shsl	SCK		MCLK* + 95	_	ns
SCK ↓→SOT delay time	t slove	SCK, SOT	External clock operation output pin :	_	2 MCLK* + 95	ns
Valid SIN→SCK↑	tivshe	SCK, SIN	C _L = 80 pF + 1 TTL	190		ns
SCK [↑] → valid SIN hold time	t shixe	SCK, SIN		MCLK* + 95	_	ns
SCK fall time	tғ	SCK		_	10	ns
SCK rise time	t R	SCK			10	ns

^{*:} Refer to "(2) Source Clock/Machine Clock" for MCLK.

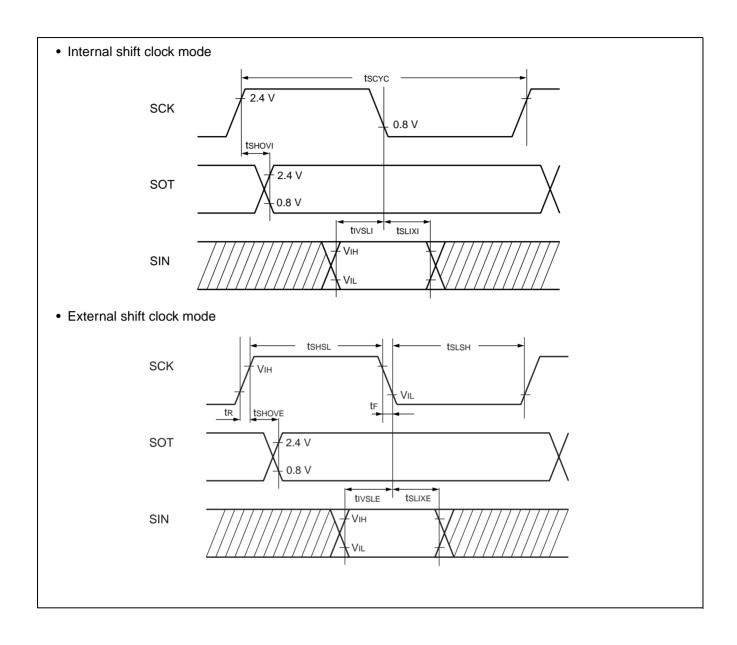


 $\mathsf{ESCR}: \mathsf{SCES} = \mathsf{1}, \, \mathsf{ECCR}: \mathsf{SCDE} = \mathsf{0}$

(Vcc = 3.3 V, AVss = Vss = 0.0 V, $T_A = -40 \, ^{\circ}\text{C}$ to $+85 \, ^{\circ}\text{C}$)

Parameter	Sym-	Pin name	Conditions	Va	lue	Unit
raiailletei	bol	Fili lialile	Conditions	Min	Max	Ollit
Serial clock cycle time	tscyc	SCK		5 MCLK*	_	ns
SCK↑→ SOT delay time	tshovi	SCK, SOT	Internal clock operation output pin :	-95	95	ns
Valid SIN→SCK↓	tıvslı	SCK, SIN	C _L = 80 pF + 1 TTL	MCLK* + 190	_	ns
$SCK \downarrow \rightarrow valid SIN hold time$	t slixi	SCK, SIN	·	0	_	ns
Serial clock "H" pulse width	t shsl	SCK		3 MCLK* - t _R	_	ns
Serial clock "L" pulse width	t slsh	SCK		MCLK* + 95	_	ns
SCK↑ →SOT delay time	t shove	SCK, SOT	External clock	_	2 MCLK* + 95	ns
Valid SIN→SCK↓	tivsle	SCK, SIN	operation output pin :	190		ns
$SCK \downarrow \rightarrow valid SIN hold time$	t SLIXE	SCK, SIN	C∟ = 80 pF + 1 TTL	MCLK* + 95	_	ns
SCK fall time	t⊧	SCK		_	10	ns
SCK rise time	t R	SCK			10	ns

^{*:} Refer to "(2) Source Clock/Machine Clock" for MCLK.

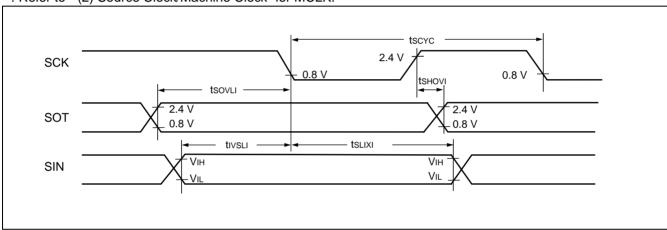


ESCR: SCES = 0, ECCR: SCDE = 1

 $(Vcc = 3.3 \text{ V}, \text{ AVss} = \text{Vss} = 0.0 \text{ V}, \text{ T}_{A} = -40 \,^{\circ}\text{C to } + 85 \,^{\circ}\text{C})$

Parameter	Sym- Pin name		Conditions	Valu	Unit	
raiailletei	bol	Finitianie	n name Conditions		Max	Onit
Serial clock cycle time	tscyc	SCK		5 MCLK*	_	ns
SCK [↑] → SOT delay time	t shovi	SCK, SOT	Internal clock	-95	95	ns
Valid SIN→SCK↓	tıvslı	SCK, SIN	operation output pin :	MCLK* + 190	_	ns
$SCK \downarrow \rightarrow valid SIN hold time$	t slixi	SCK, SIN	C∟ = 80 pF + 1 TTL	0	_	ns
SOT→SCK↓ delay time	tsovli	SCK, SOT		_	4 MCLK*	ns

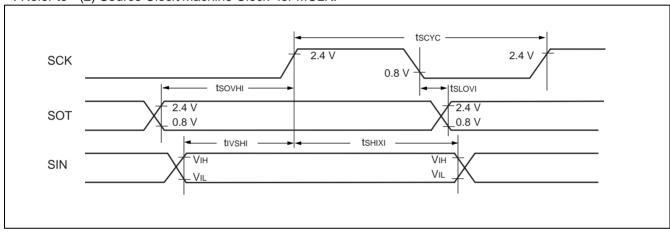
*: Refer to "(2) Source Clock/Machine Clock" for MCLK.



ESCR: SCES = 1, ECCR: SCDE = 1

Parameter	Sym-	Pin name	Conditions	Valu	Unit	
Parameter	Parameter Symbol Pin name Conditions		Min	Max	Onit	
Serial clock cycle time	tscyc	SCK		5 MCLK*		ns
SCK↓→SOT hold time	t slovi	SCK, SOT	Internal clock	-95	95	ns
Valid SIN→SCK↑	t ıvshı	SCK, SIN	operating output pin:	MCLK* + 190	_	ns
$SCK \uparrow \rightarrow valid SIN hold time$	t shixi	SCK, SIN	C _L = 80 pF + 1 TTL	0	_	ns
SOT→SCK [↑] delay time	tsovні	SCK, SOT		_	4 MCLK*	ns

*: Refer to "(2) Source Clock/Machine Clock" for MCLK.

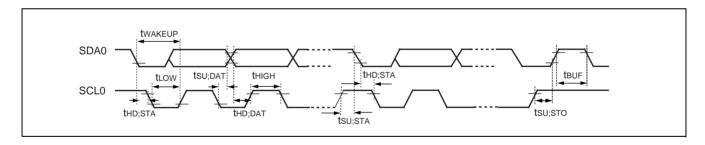


(8) I2C Timing

(Vcc = 3.3 V, AVss = Vss = 0.0 V,
$$T_A = -40 \,^{\circ}\text{C}$$
 to $+85 \,^{\circ}\text{C}$)

				Val	ue			
Parameter	Symbol	Conditions	Standard-mode		Fast-mode		Unit	Remarks
			Min	Max	Min	Max		
SCL clock frequency	fscL		0	100	0	400	kHz	
(Repeat) Start condition hold time SDA $\downarrow \rightarrow$ SCL \downarrow	t hd;sta		4.0		0.6	_	μs	
SCL clock "L" width	t LOW		4.7	_	1.3	_	μs	
SCL clock "H" width	t HIGH		4.0	_	0.6	_	μs	
(Repeat) Start condition setup time SCL $\uparrow \rightarrow$ SDA \downarrow	t su;sta	$R = 1.7 \text{ k}Ω,$ $C = 50 \text{ pF}^{*1}$	4.7		0.6	_	μs	
Data hold time SCL \downarrow \rightarrow SDA \downarrow \uparrow	thd;dat	0 – 00 рі	0	3.45*2	0	0.9*3	μs	
Data setup time SDA $\downarrow \uparrow \rightarrow$ SCL \uparrow	t su;dat		0.25	_	0.1	_	μs	
Stop condition setup time SCL $\uparrow \rightarrow$ SDA \uparrow	t su;sто		4		0.6	_	μs	
Bus free time between stop condition and start condition	t BUF		4.7	_	1.3	_	μs	

- *1: R, C: Pull-up resistor and load capacitor of the SCL and SDA lines.
- *2: The maximum thd; DAT have only to be met if the device dose not stretch the "L" width (tLow) of the SCL signal.
- *3 : A Fast-mode I²C-bus device can be used in a Standard-mode I²C-bus system, but the requirement $t_{SU;DAT} \ge 250$ ns must then be met.



(Vcc = 3.3 V, AVss = Vss = 0.0 V, $T_{\text{A}} = -40~^{\circ}\text{C}$ to ~+ 85 $^{\circ}\text{C})$

Davamatar	Sym-	I/O Ti	ming	I Imia	Domarka
Parameter	bol	Min	Max	Unit	Remarks
SCL clock "L" width	t LOW	(2 + nm* ² / 2) MCLK* ¹ – 20	_	ns	Master mode
SCL clock "H" width	t HIGH	(nm*2 / 2) MCLK*1 – 20	(nm*² / 2) MCLK*1 + 20	ns	Master mode
Start condition hold time	thd;sta	(-1 + nm* ² / 2) MCLK* ^{ñ1} - 20	(-1 + nm*²) MCLK*¹ + 20	ns	Master mode Maximum value is applied when m, n = 1, 8. Otherwise, the minimum value is applied.
Stop condition setup time	t su;sto	(1 + nm*2 / 2) MCLK*ñ1 - 20	(1 + nm*2 / 2) MCLK*1 + 20	ns	Master mode
Start condition setup time	t su;sta	(1 + nm* ² / 2) MCLK* ¹ – 20	(1 + nm*2 / 2) MCLK*1 + 20	ns	Master mode
Bus free time between stop condition and start condition	t BUF	(2 nm*2 + 4) MCLK*1 - 20	_	ns	
Data hold time	thd;dat	3 MCLK*1 – 20	_	ns	Master mode
Data setup time	tsu;dat	(-2 + nm* ² / 2) MCLK* ¹ - 20	(-1 + nm* ² / 2) MCLK* ¹ + 20	ns	Master mode When assuming that "L" of SCL is not extended, the minimum value is applied to first bit of continuous data. Otherwise, the maximum value is applied.
Setup time between clearing interrupt and SCL rising	tsu;ınt	(nm*2 / 2) MCLK*1 – 20	(1 + nm* ² / 2) MCLK* ¹ + 20	ns	Minimum value is applied to interrupt at 9th SCL↓. Maximum value is applied to interrupt at 8th SCL↓.
SCL clock "L" width	t LOW	4 MCLK*1 – 20		ns	At reception
SCL clock "H" width	t HIGH	4 MCLK*1 – 20		ns	At reception
Start condition detection	thd;sta	2 MCLK*1 – 20	_	ns	Undetected when 1 MCLK is used at reception
Stop condition detection	t su;sto	2 MCLK*1 – 20	_	ns	Undetected when 1 MCLK is used at reception
Restart condition detection condition	t su;sta	2 MCLK*1 – 20	_	ns	Undetected when 1 MCLK is used at reception
Bus free time	t BUF	2 MCLK*1 – 20	_	ns	At reception
Data hold time	thd;dat	2 MCLK*1 – 20	_	ns	At slave transmission mode
Data setup time	t su;dat	tLow – 3 MCLK*1 – 20	_	ns	At slave transmission mode
Data hold time	t hd;dat	0	<u> </u>	ns	At reception
Data setup time	t su;dat	MCLK*1 - 20	_	ns	At reception

(Continued)

(Continued)

(Vcc = 3.3 V, AVss = Vss = 0.0 V,
$$T_A = -40 \,^{\circ}\text{C}$$
 to + 85 $^{\circ}\text{C}$)

Parameter	Sym-	I/O Ti	ming	Unit	Remarks
i arameter	bol	Min	Max	Oint	Kemarks
SDA↓→SCL↑ (at wakeup function)	t WAKE- UP	Oscillation stabilization wait time + 2 MCLK*1 – 20	_	ns	

- *1: Refer to "(2) Source Clock/Machine Clock" for MCLK.
- *2: m is CS4 bit and CS3 bit (bit 4 and bit 3) of clock control register (ICCR).
 - n is CS2 bit to CS0 bit (bit 2 to bit 0) of clock control register (ICCR).
 - Actual timing of I²C is determined by m and n values set by the machine clock (MCLK) and ICCR [4:0].
 - Standard-mode:

m and n can be set at the range : 0.9 MHz < MCLK (machine clock) < 10 MHz. Setting of m and n determines the machine clock that can be used below.

• Fast-mode :

m and n can be set at the range : 3.3 MHz < MCLK (machine clock) < 10 MHz. Setting of m and n determines the machine clock that can be used below.

```
\begin{array}{lll} (m,\,n) \,=\, (1,\,8) & : 3.3 \; MHz < MCLK \leq 4 \; MHz \\ (m,\,n) \,=\, (1,\,22) \;,\; (5,\,4) \;: 3.3 \; MHz < MCLK \leq 8 \; MHz \\ (m,\,n) \,=\, (6,\,4) & : 3.3 \; MHz < MCLK \leq 10 \; MHz \end{array}
```

5. A/D Converter

(1) A/D Converter Electrical Characteristics

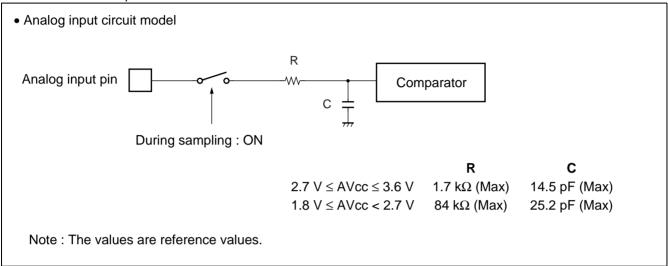
(AVcc = Vcc = 1.8 V to 3.3 V [FLASH product], AVcc = Vcc = 1.8 V to 3.6 V [MASK product], AVss = Vss = 0.0 V, $T_A = -40$ °C to +85 °C)

Danamatan	Comple at	Value				D
Parameter	Symbol	Min	Тур	Max	Unit	Remarks
Resolution		_	_	10	bit	
Total error]	- 3.0	_	+ 3.0	LSB	
Linearity error		- 2.5	_	+ 2.5	LSB	
Differential linear error		- 1.9	_	+ 1.9	LSB	
Zero transition voltage	Vот	AVss – 1.5 LSB	AVss + 0.5 LSB	AVss + 2.5 LSB	V	FLASH product : 2.7 V ≤ AVcc ≤ 3.3 V MASK product : 2.7 V ≤ AVcc ≤ 3.6 V
		AVss – 0.5 LSB	AVss + 1.5 LSB	AVss + 3.5 LSB	V	1.8 V ≤ AVcc < 2.7 V
Full-scale transition voltage	VFST	AVR – 3.5 LSB	AVR – 1.5 LSB	AVR + 0.5 LSB	V	FLASH product : 2.7 V ≤ AVcc ≤ 3.3 V MASK product : 2.7 V ≤ AVcc ≤ 3.6 V
		AVR – 2.5 LSB	AVR – 0.5 LSB	AVR + 1.5 LSB	V	1.8 V ≤ AVcc < 2.7 V
Compare time	_	0.6	_	16,500	μs	FLASH product : 2.7 V ≤ AVcc ≤ 3.3 V MASK product : 2.7 V ≤ AVcc ≤ 3.6 V
		20		16,500	μs	1.8 V ≤ AVcc < 2.7 V
Sampling time		0.4		œ	μs	FLASH product : 2.7 V \leq AVcc \leq 3.3 V MASK product : 2.7 V \leq AVcc \leq 3.6 V external impedance $<$ at 1.8 k Ω
		30	_	80	μs	$1.8 \text{ V} \leq \text{AVcc} < 2.7 \text{ V}$ external impedance < at 14.8 k Ω
Analog input current	Iain	-0.3	_	0.3	μΑ	
Analog input voltage range	Vain	AVss		AVR	V	
Reference voltage	_	AVss + 1.8	_	AVcc	V	AVR pin
Reference voltage	IR	_	400	600	μА	AVR pin, During A/D operation
supply current	I RH	_	_	5	μА	AVR pin, At stop mode

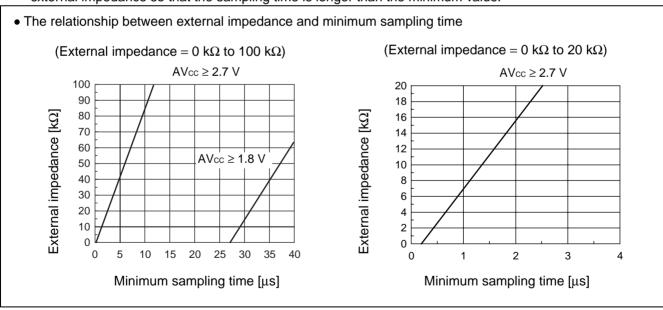
(2) Notes on Using A/D Converter

• About the external impedance of analog input and its sampling time

• A/D converter with sample and hold circuit. If the external impedance is too high to keep sufficient sampling time, the analog voltage charged to the internal sample and hold capacitor is insufficient, adversely affecting A/D conversion precision.



• To satisfy the A/D conversion precision standard, consider the relationship between the external impedance and minimum sampling time and either adjust the resistor value and operating frequency or decrease the external impedance so that the sampling time is longer than the minimum value.



• If the sampling time cannot be sufficient, connect a capacitor of about 0.1 μF to the analog input pin.

About errors

As |AVR - AVss| becomes smaller, values of relative errors grow larger.

(3) Definition of A/D Converter Terms

Resolution

The level of analog variation that can be distinguished by the A/D converter.

When the number of bits is 10, analog voltage can be divided into $2^{10} = 1024$.

• Linearity error (unit : LSB)

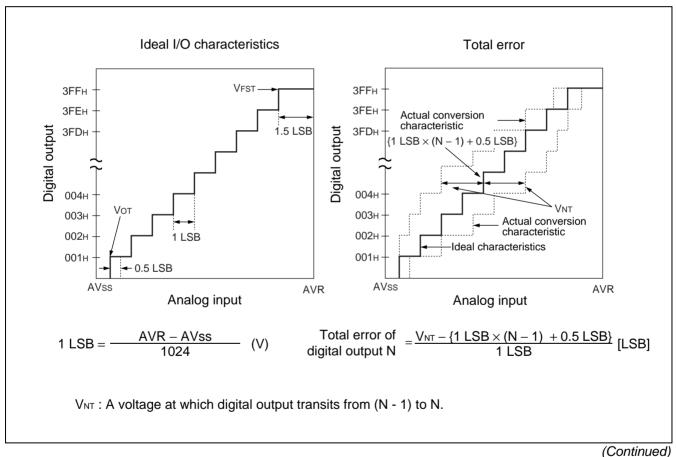
The deviation between the value along a straight line connecting the zero transition point ("00 0000 0000" ← \rightarrow "00 0000 0001") of a device and the full-scale transition point ("11 1111 1111" \leftarrow \rightarrow "11 1111 1110") compared with the actual conversion values obtained.

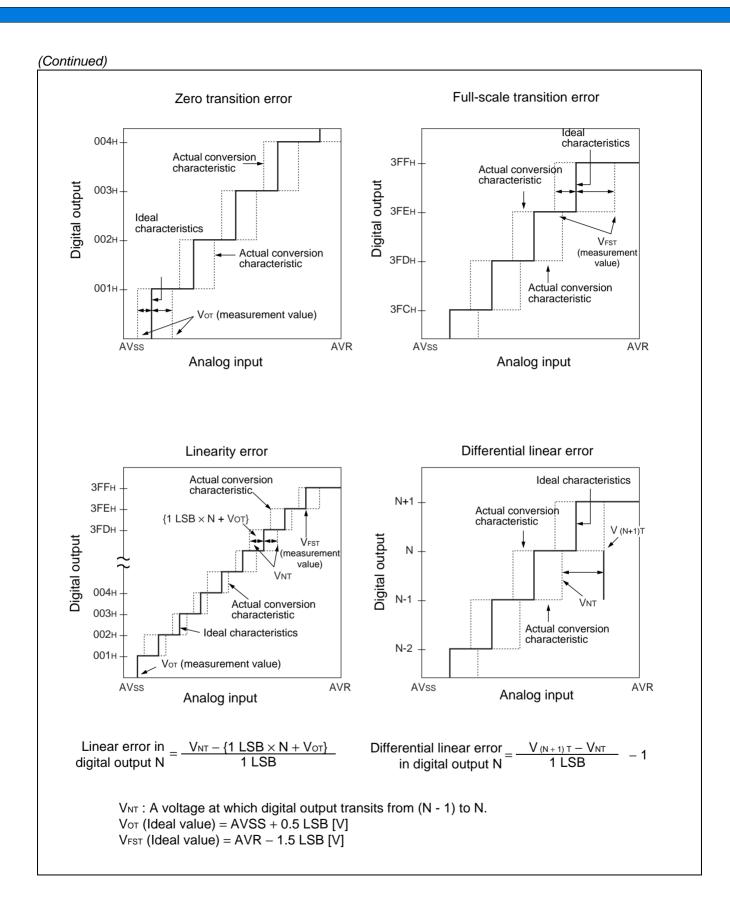
• Differential linear error (Unit: LSB)

Deviation of input voltage, which is required for changing output code by 1 LSB, from an ideal value.

• Total error (unit: LSB)

Difference between actual and theoretical values, caused by a zero transition error, full-scale transition error, linearity error, quantum error, and noise.





6. Flash Memory Program/Erase Characteristics

Parameter	Value			1164	Domonico	
Parameter	Min	Тур	Max	Unit	Remarks	
Sector erase time (4 KB sector)	_	0.2*1	3*2	s	Excludes 00 _H programming prior erasure.	
Sector erase time (16 KB sector)		0.5*1	12*2	s	Excludes 00 _H programming prior erasure.	
Byte programming time		32	3600	μs	Excludes system-level overhead.	
Erase/program cycle	10,000	_	_	cycle		
Power supply voltage at erase/ program	2.7		3.3	V		
Flash data retension time	20*3	_	_	year	Average T _A = +85 °C	

^{*1 :} $T_A = +25 \, {}^{\circ}C$, $V_{CC} = 3.0 \, V$, 10000 cycles

^{*2 :} $T_A = +85 \, ^{\circ}\text{C}$, $V_{CC} = 2.7 \, \text{V}$, 10000 cycles

 $^{^*3}$: This value comes from the technology qualification (using Arrhenius equation to translate high temperature measurements into normalized value at +85 $^{\circ}$ C).

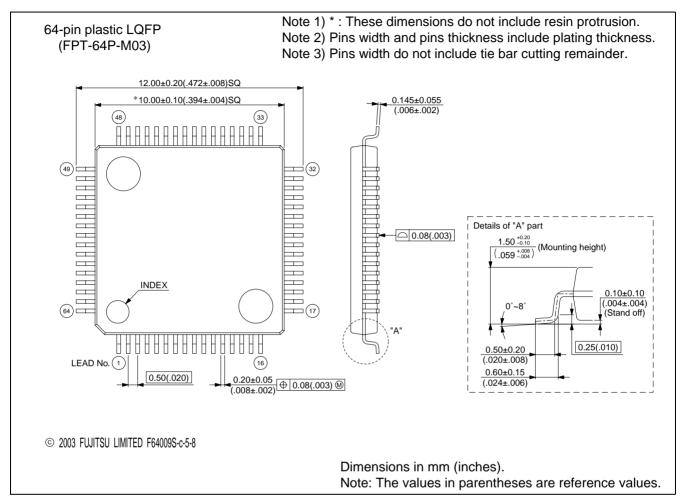
■ MASK OPTION

	Part number	MB95107A	MB95F108AS	MB95F108AW	MB95FV100A-101
No.	Specifying procedure	Specify when ordering MASK Setting disable		Setting disabled	Setting disabled
1	Clock mode select Single-system clock mode Dual-system clock mode	Selectable	Single-system clock mode	Dual-system clock mode	Changing by the switch on MCU board
2	Selection of oscillation stabilization wait time • Selectable the initial value of main clock oscillation stabili- zation wait time	Selectable 1: (2²-2) /Fch 2: (2¹²-2) /Fch 3: (2¹³-2) /Fch 4: (2¹⁴-2) /Fch	Fixed to oscillation stabilization wait time of (214-2) /FcH	Fixed to oscillation stabilization wait time of (214-2) /FcH	Fixed to oscillation stabilization wait time of (2 ¹⁴ -2) /F _{CH}

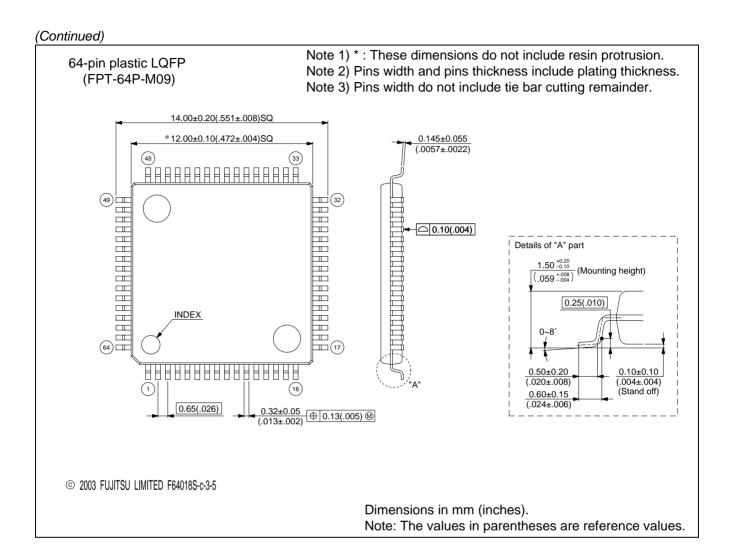
■ ORDERING INFORMATION

Part number	Package	Remarks
MB95107APFV MB95F108ASPFV MB95F108AWPFV	64-pin plastic LQFP (FPT-64P-M03)	
MB95107APFM MB95F108ASPFM MB95F108AWPFM	64-pin plastic LQFP (FPT-64P-M09)	
MB2146-301 (MB95FV100A-101PBT)	MCU board (224-pin plastic PFBGA (BGA-224P-M08)	

■ PACKAGE DIMENSIONS



(Continued)



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